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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2814
Examiner: Dana FARAHANI

In Reply, Please Refer to the Following Patent Application Of:

Applicant(s): Yoshinori SHIZUNO

Serial No.: 09/705,729

Filed: November 6, 2000

For: SEMICONDUCTOR DEVICE AND METHOD
OF MANUFACTURING THE SAME

Docket No.: OKI-267

AMENDMENT

July 19, 2002

Assistant Commissioner of
Patents and Trademarks
Washington, D.C. 20231

Sir:

In response to the Examiner's Action mailed on April 24, 2002, please amend the
above-identified application as follows:

IN THE SPECIFICATION:

Please amend the specification as follows:

Page 2, please replace the second paragraph bridging lines 7-18 with the
following replacement paragraph:

--This type of semiconductor device includes a semiconductor chip 1 on which,
although not illustrated in the drawing, circuits and bonding pads are formed, a multi-
layer wiring substrate or board 2 on which, although not shown in the drawing, bonding
posts, circuits and through holes are formed in positions corresponding to the respective
pads, a heat spreader 3 to which the semiconductor chip 1 and the wiring board 2 are
fixed, metal thin wires 4 for connecting the pads and the posts respectively, and an

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